

Title (en)  
CONDUCTOR CONNECTING MODULE FOR PRINTED CIRCUIT BOARDS

Title (de)  
ADERANSCHLUSSMODUL FÜR LEITERPLATTEN

Title (fr)  
MODULE DE CONNEXION DE CONDUCTEURS POUR DES CARTES A CIRCUITS IMPRIMES

Publication  
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Application  
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Abstract (en)  
[origin: US2007111555A1] The invention relates to a conductor connecting module for printed circuit boards, comprising a housing in which contact elements are disposed. Said contact elements have a first contact area that is configured as an insulation displacement contact, and a second contact area that is configured as a solderable contact pin. The contact pins are disposed at a right angle to the insulation displacement contacts so that the insulation displacement contacts, in the mounted state, lie in a plane parallel to the printed circuit board.

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